

Hong Kong Exchanges and Clearing Limited and The Stock Exchange of Hong Kong Limited take no responsibility for the contents of this announcement, make no representation as to its accuracy or completeness and expressly disclaim any liability whatsoever for any loss howsoever arising from or in reliance upon the whole or any part of the contents of this announcement.



HUA HONG SEMICONDUCTOR LIMITED

華虹半導體有限公司

(Incorporated in Hong Kong with limited liability)

Stock Code (01347)

News Release

Reports 2025 First Quarter Results

*All currency figures in this report are in US Dollars unless indicated otherwise.
The consolidated financial statements are prepared in accordance with HKFRS.*

Hong Kong Special Administrative Region of the People's Republic of China – May 8, 2025.

Hua Hong Semiconductor Limited (SEHK: 01347; SSE STAR MARKET: 688347) (the "Company"), a global, leading pure-play foundry, today announced its consolidated operational results for the quarter ending March 31, 2025.

First Quarter 2025 Highlights (Unaudited)

- Revenue was US\$540.9 million, 17.6% over 1Q 2024 and 0.3% above 4Q 2024.
- Gross margin was 9.2%, 2.8 percentage points over 1Q 2024 and 2.2 percentage points lower than 4Q 2024.
- Net profit attributable to shareholders of the parent company was US\$3.8 million, compared to US\$31.8 million in 1Q 2024 and net loss attributable to shareholders of the parent company of US\$25.2 million in 4Q 2024.

Second Quarter 2025 Guidance

- We expect revenue to be approximately US\$550 million to US\$570 million.
- We expect gross margin to be in the range of 7% to 9%.

President's Message

Dr. Peng Bai, President and Executive Director of the Company, commented on the performance of the first quarter of 2025:

"First quarter 2025 sales revenue for Hua Hong Semiconductor was 541 million US dollars, and gross margin reached 9.2%, both in line with guidance. Overall performance has continued the trend from 2024. Sales revenue maintained steady growth; the product portfolio has been continuously optimized; and the utilization rate has remained at full capacity. The capacity ramp-up of the second 12" production line is in line with our expectation, which has positive implications for subsequent revenue growth, product portfolio optimization and enhancement of the company's core competitiveness."

President Bai continued, "From market perspective, customer demand and competitive landscape have essentially continued the trend since the second half of 2024. However, due to recent changes in the global environment and related policies, the entire semiconductor industry will face greater uncertainties in terms of customer demand, procurement costs, and the supply chain landscape. In the face of such uncertainties, Hua Hong Semiconductor will adhere to its strategy of continuously accelerating effective capacity expansion, enhancing its R&D capabilities, actively exploring marketing opportunities, timely managing possible disturbances from the supply side, intensively reduce cost and improve efficiency, to reduce risks while achieving better performance. "

Webcast/Conference Call Announcement

Date: Thursday, May 8, 2025

Time: 17:00 Hong Kong/Shanghai Time
05:00 EST

Presenters: Dr. Peng Bai, President and Executive Director
Mr. Daniel Wang, Executive Vice President and Chief Financial Officer

Webcast: The call will be webcast live with audio and slides at:
https://www.huahonggrace.com/html/ir_calendar.php or
<https://edge.media-server.com/mmc/p/gp3biy2m>

(Note: registration is required to access the webcast.)

Dial-in Details: Please register in advance of the conference using the link provided below. Upon registering, you will be provided with participant dial-in numbers and personal PIN.

<https://register-conf.media-server.com/register/BI51cfe11dc7f540f2af2ea9635eedb78c>

Important Note: Before the meeting starts, you will need the personal PIN to join the call. Please check and save the confirmation email after registering. For security reasons, please do not share your personal PIN with anyone else.

Replay: A recording will be available for replay at the below website about 2 hours after the event and will be available for 12 months.

https://www.huahonggrace.com/html/ir_calendar.php

About the Company

Hua Hong Semiconductor Limited (Stock Code: 688347.SH/ 01347.HK) (the "Company") is a global leading pure-play foundry with specialty technologies which offers a diverse array of wafer foundry and supporting services to its customers, implementing "8-inch + 12-inch" and advanced "Specialty IC + Power Discrete" development strategies. The Company focuses on continuous innovation of specialty technologies, including embedded/standalone non-volatile memory (NVM), power discrete, analog & power management, and logic & RF, supporting applications in emerging areas, such as new energy vehicles, green energy, and the Internet of Things. Of special note is the Company's outstanding quality control system that satisfies the strict requirements of automotive chip manufacturing. The Company is a member of the Hua Hong Group, which is an industrial group in China that owns mainstream "8-inch + 12-inch" advanced IC manufacturing process technologies.

The Company operates three 8-inch wafer fabrication facilities in Shanghai Jinqiao and Shanghai Zhangjiang. In addition, the Company has built two global leading 12-inch wafer fabrication facilities devoted to specialty processes in Wuxi National Hi-Tech District, one of which is the world's first 12-inch power semiconductor foundry.

For more information, please visit: www.huahonggrace.com.

Summary of Operating Results
(Amounts in US\$ thousands, except for EPS and operating data)

	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)	YoY Change	QoQ Change
Revenue	540,937	459,986	539,177	17.6 %	0.3 %
Gross profit	49,997	29,632	61,426	68.7 %	(18.6)%
Gross margin	9.2 %	6.4 %	11.4 %	2.8	(2.2)
Operating expenses	(97,110)	(78,520)	(110,626)	23.7 %	(12.2)%
Other (loss) / income net	(8,294)	3,770	(40,468)	(320.0)%	(79.5)%
Loss before tax	(55,407)	(45,118)	(89,668)	22.8 %	(38.2)%
Income tax credit / (expense)	3,245	19,832	(6,596)	(83.6)%	(149.2)%
Loss for the period	(52,162)	(25,286)	(96,264)	106.3 %	(45.8)%
Net profit margin	(9.6)%	(5.5)%	(17.9)%	(4.1)	8.3
Attributable to:					
Owners of the parent	3,750	31,818	(25,199)	(88.2)%	(114.9)%
Non-controlling interests	(55,912)	(57,104)	(71,065)	(2.1)%	(21.3)%
Earnings per share attributable to owners of the parent					
Basic	0.002	0.019	(0.015)	(89.5)%	(113.3)%
Diluted	0.002	0.019	(0.015)	(89.5)%	(113.3)%
Wafers shipped (in thousands 8" equivalent wafers)	1,231	1,026	1,213	20.0 %	1.5 %
Capacity utilization ¹	102.7 %	91.7 %	103.2 %	11.0	(0.5)
ROE ²	0.4 %	2.0 %	(1.6)%	(1.6)	2.0

First Quarter 2025

- Revenue was US\$540.9 million, 17.6% over 1Q 2024, primarily driven by increased wafer shipments, and 0.3% over 4Q 2024.
- Gross margin was 9.2%, 2.8 percentage points over 1Q 2024, primarily driven by improved capacity utilization, partially offset by increased depreciation costs, and 2.2 percentage points lower than 4Q 2024, primarily due to increased depreciation costs.
- Operating expenses were US\$97.1 million, 23.7% over 1Q 2024, primarily due to increased engineering wafer costs, and 12.2% lower than 4Q 2024, primarily due to decreased labor expense, partially offset by increased engineering wafer costs.
- Other loss net was US\$8.3 million, compared to other income net of US\$3.8 million in 1Q 2024, primarily due to increased foreign exchange losses and decreased interest income, partially offset by increased government subsidies. The loss was 79.5% lower than 4Q 2024, primarily due to decreased foreign exchange losses and increased government subsidies.
- Income tax credit was US\$3.2 million, compared to US\$19.8 million in 1Q 2024, primarily due to decreased reversal of dividend withholding tax.
- Net loss for the period was US\$52.2 million, compared to US\$25.3 million in 1Q 2024 and US\$96.3 million in 4Q 2024.
- Net profit attributable to shareholders of the parent company was US\$3.8 million, compared to US\$31.8 million in 1Q 2024 and net loss attributable to shareholders of the parent company of US\$25.2 million in 4Q 2024.
- Basic earnings per share was US\$0.002, compared to US\$0.019 in 1Q 2024 and US\$-0.015 in 4Q 2024.
- ROE (annualized) was 0.4%, compared to 2.0% in 1Q 2024 and -1.6% in 4Q 2024 respectively.

¹The capacity utilization is calculated based on average monthly equivalent wafers output divided by total estimated monthly capacity.

²Profit attributable to owners of the parent / weighted average net assets attributable to owners of the parent.

Analysis of Revenue

Revenue by service type	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
Wafers	515,574	95.3 %	437,060	95.0 %	78,514	18.0 %
Others	25,363	4.7 %	22,926	5.0 %	2,437	10.6 %
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- 95.3% of total revenue was derived from the sale of semiconductor wafers in 1Q 2025.

Analysis of Revenue

Revenue by wafer size	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
8" wafers	231,086	42.7 %	239,950	52.2 %	(8,864)	(3.7)%
12" wafers	309,851	57.3 %	220,036	47.8 %	89,815	40.8 %
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- *Revenues from 8" wafers and 12" wafers were US\$231.1 million and US\$309.9 million, respectively, in 1Q 2025.*

Analysis of Revenue

Revenue by geography	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
China ³	442,458	81.8 %	365,695	79.5 %	76,763	21.0 %
North America ⁴	56,427	10.4 %	46,241	10.1 %	10,186	22.0 %
Asia ⁵	25,784	4.8 %	23,566	5.1 %	2,218	9.4 %
Europe	15,228	2.8 %	21,739	4.7 %	(6,511)	(30.0)%
Japan ⁶	1,040	0.2 %	2,745	0.6 %	(1,705)	(62.1)%
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- *Revenue from China* was US\$442.5 million, contributing 81.8% of total revenue and an increase of 21.0% compared to 1Q 2024, mainly driven by increased demand for super junction, other PMIC, flash, general MOSFET, smart card IC and logic products.
- *Revenue from North America* was US\$56.4 million, an increase of 22.0% compared to 1Q 2024, mainly driven by increased demand for other PMICs.
- *Revenue from Asia* was US\$25.8 million, an increase of 9.4% compared to 1Q 2024, mainly driven by increased demand for MCU products.
- *Revenue from Europe* was US\$15.2 million, a decrease of 30.0% compared to 1Q 2024, mainly due to decreased demand for IGBT, smart card IC and general MOSFET products.
- *Revenue from Japan* was US\$1.0 million, a decrease of 62.1% compared to 1Q 2024, primarily due to decreased demand for super junction products.

³Includes Chinese Mainland and Hong Kong.

⁴Includes a major customer in US that was acquired by an Europe headquartered company in 2020.

⁵Excludes China and Japan.

⁶Includes a major customer in Japan that was acquired by a U.S. headquartered company in 2013.

Analysis of Revenue

Revenue by technology platform	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
Embedded NVM	130,290	24.1 %	119,214	25.9 %	11,076	9.3 %
Standalone NVM	42,875	7.9 %	31,072	6.8 %	11,803	38.0 %
Power Discrete	162,751	30.1 %	143,344	31.1 %	19,407	13.5 %
Logic & RF	66,787	12.3 %	64,213	14.0 %	2,574	4.0 %
Analog & PM	136,784	25.3 %	101,495	22.1 %	35,289	34.8 %
Others	1,450	0.3 %	648	0.1 %	802	123.8 %
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- *Revenue from embedded NVM* was US\$130.3 million, an increase of 9.3% compared to 1Q 2024, mainly driven by increased demand for smart card IC and MCU products.
- *Revenue from standalone NVM* was US\$42.9 million, an increase of 38.0% compared to 1Q 2024, mainly driven by increased demand for flash products.
- *Revenue from power discrete* was US\$162.8 million, an increase of 13.5% compared to 1Q 2024, mainly driven by increased demand for super junction and general MOSFT products.
- *Revenue from logic & RF* was US\$66.8 million, an increase of 4.0% over 1Q 2024, mainly driven by increased demand for logic products.
- *Revenue from analog & power management* was US\$136.8 million, an increase of 34.8% over 1Q 2024, mainly driven by increased demand for other PMIC products.

Analysis of Revenue

Revenue by process technology node	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
≤65nm	124,280	23.0 %	94,477	20.6 %	29,803	31.5 %
90nm & 95nm	128,864	23.8 %	88,516	19.2 %	40,348	45.6 %
0.11μm & 0.13μm	54,059	10.0 %	71,430	15.5 %	(17,371)	(24.3)%
0.15μm & 0.18μm	29,938	5.5 %	29,915	6.5 %	23	0.1 %
0.25μm	3,517	0.7 %	7,617	1.7 %	(4,100)	(53.8)%
≥0.35μm	200,279	37.0 %	168,031	36.5 %	32,248	19.2 %
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- Revenue from 65nm and below technology nodes was US\$124.3 million, an increase of 31.5% over 1Q 2024, mainly driven by increased demand for flash and logic products.
- Revenue from the 90nm & 95nm technology nodes was US\$128.9 million, an increase of 45.6% over 1Q 2024, mainly driven by increased demand for other PMIC and MCU products.
- Revenue from the 0.11μm & 0.13μm technology nodes was US\$54.1 million, a decrease of 24.3% compared to 1Q 2024, mainly due to decreased demand for smart card IC and MCU products.
- Revenue from the 0.15μm & 0.18μm technology nodes was US\$29.9 million, an increase of 0.1% compared to 1Q 2024.
- Revenue from the 0.25μm technology node was US\$3.5 million, a decrease of 53.8% compared to 1Q 2024, mainly due to decreased demand for general MOSFET and RF products.
- Revenue from the 0.35μm and above technology nodes was US\$200.3 million, an increase of 19.2% compared to 1Q 2024, mainly driven by increased demand for super junction, general MOSFET, and smart card ICs.

Analysis of Revenue

Revenue by end market distribution	1Q 2025 US\$000 (Unaudited)	1Q 2025 % (Unaudited)	1Q 2024 US\$000 (Unaudited)	1Q 2024 % (Unaudited)	YoY Change US\$000	YoY Change %
Consumer electronics	348,100	64.3 %	287,863	62.6 %	60,237	20.9 %
Industrial & automotive	119,878	22.2 %	102,723	22.3 %	17,155	16.7 %
Communications	65,264	12.1 %	61,204	13.3 %	4,060	6.6 %
Computing	7,695	1.4 %	8,196	1.8 %	(501)	(6.1)%
Total revenue	540,937	100.0 %	459,986	100.0 %	80,951	17.6 %

- *Revenue from consumer electronics*, our largest end market segment, contributed US\$348.1 million, reaching 64.3% of total revenue, an increase of 20.9% over 1Q 2024, mainly driven by increased demand for super junction, other PMIC, flash, general MOSFET and logic products.
- *Revenue from industrial & automotive* was US\$119.9 million, an increase of 16.7% compared to 1Q 2024, mainly driven by increased demand for other PMICs.
- *Revenue from communications* was US\$65.3 million, an increase of 6.6% compared to 1Q 2024, mainly driven by increased demand for analog products.
- *Revenue from computing* was US\$7.7 million, a decrease of 6.1% compared to 1Q 2024.

Capacity⁷ and Capacity Utilization

	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)
Total capacity (in thousands 8" equivalent wafers)	413	391	391
Overall capacity utilization	102.7%	91.7%	103.2%

- Monthly capacity was 413,000 8-inch equivalent wafers at the end of 1Q 2025. Overall capacity utilization was 102.7% in 1Q 2025, 0.5 percentage points lower than 4Q 2024.

Wafer Shipments

in thousands 8" equivalent wafers	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)	YoY Change	QoQ Change
Wafer shipments	1,231	1,026	1,213	20.0 %	1.5 %

- *Wafer shipments* were 1,231,000, an increase of 20.0% year over year, and 1.5% quarter over quarter.

⁷ Wafers per month at the end of the period, calculated on a 30-day basis for comparison purposes.

Operating Expenses Analysis

Amounts in US\$ thousands	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)	YoY Change	QoQ Change
Selling and distribution expenses	2,214	1,985	2,617	11.5 %	(15.4)%
Administrative expenses ⁸	94,896	76,535	108,009	24.0 %	(12.1)%
Operating expenses	97,110	78,520	110,626	23.7 %	(12.2)%

- *Operating expenses* were US\$97.1 million, 23.7% over 1Q 2024, primarily due to increased engineering wafer costs, and 12.2% lower than 4Q 2024, primarily due to decreased labor expense, partially offset by increased engineering wafer costs.

Other (Loss) / Income Net Analysis

Amounts in US\$ thousands	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)	YoY Change	QoQ Change
Rental income	3,513	3,560	3,481	(1.3)%	0.9 %
Interest income	15,619	25,020	20,450	(37.6)%	(23.6)%
Foreign exchange losses	(16,199)	(5,850)	(48,664)	176.9 %	(66.7)%
Share of profit / (loss) of associates	652	1,411	(433)	(53.8)%	(250.6)%
Finance costs	(23,301)	(24,585)	(20,406)	(5.2)%	14.2 %
Government subsidies	11,231	3,799	4,705	195.6 %	138.7 %
Others	191	415	399	(54.0)%	(52.1)%
Other (loss) / income net	(8,294)	3,770	(40,468)	(320.0)%	(79.5)%

- *Other loss net* was US\$8.3 million, compared to other income net of US\$3.8 million in 1Q 2024, primarily due to increased foreign exchange losses and decreased interest income, partially offset by increased government subsidies. The loss was 79.5% lower than 4Q 2024, primarily due to decreased foreign exchange losses and increased government subsidies.

⁸Administrative expenses include government grants recognized as an offset item.

Cash Flow Analysis

Amounts in US\$ thousands	1Q 2025 (Unaudited)	1Q 2024 (Unaudited)	4Q 2024 (Unaudited)	YoY Change	QoQ Change
Net cash flows generated from operating activities	50,186	40,660	308,108	23.4 %	(83.7)%
Net cash flows used in investing activities	(494,291)	(298,951)	(1,444,013)	65.3 %	(65.8)%
Net cash flows generated from / (used in) financing activities	59,137	789,913	(50,929)	(92.5)%	(216.1)%
Effect of exchange rate changes	5,771	(8,817)	(120,783)	(165.5)%	(104.8)%
Net change in cash	(379,197)	522,805	(1,307,617)	(172.5)%	(71.0)%

- *Net cash flows generated from operating activities* was US\$50.2 million, 23.4% over 1Q 2024, primarily due to increased receipts from customers, and 83.7% lower than 4Q 2024, primarily due to decreased receipts of government grants and increased payments of materials and income tax.
- *Net cash flows used in investing activities* was US\$494.3 million, including US\$510.9 million investment in fixed assets, partially offset by US\$16.6 million interest income.
- *Net cash flows generated from financing activities* was US\$59.1 million, including US\$861.0 million proceeds from bank borrowings and US\$13.1 million proceeds from share option exercises, partially offset by US\$811.2 million of bank principal repayments, US\$3.3 million interest payments and US\$0.5 million lease payments.

Capital Structure

Amounts in US\$ thousands	31-Mar-2025 (Unaudited)	31-Dec-2024 (Audited)
Total assets	12,286,786	12,415,108
Total liabilities	3,406,124	3,508,489
Total equity	8,880,662	8,906,619
<i>Debt ratio⁹</i>	27.7%	28.3%

Capital Expenditures

Amounts in US\$ thousands	1Q 2025 (Unaudited)	4Q 2024 (Unaudited)
Hua Hong 8"	14,264	21,159
Hua Hong Wuxi	18,402	43,833
Hua Hong Manufacturing	478,185	1,440,717
Total	510,851	1,505,709

- *Capital expenditures* were US\$510.9 million in 1Q 2025, including US\$478.2 million for Hua Hong Manufacturing, US\$18.4 million for Hua Hong Wuxi, and US\$14.3 million for Hua Hong 8".

⁹ Debt ratio is calculated based on total liabilities / total assets.

Liquidity

Amounts in US\$ thousands	31-Mar-2025 (Unaudited)	31-Dec-2024 (Audited)
Properties under development	221,061	221,905
Inventories	468,597	467,060
Trade and notes receivables	286,763	270,461
Prepayments, other receivables and other assets	411,207	363,997
Due from related parties	16,520	18,324
Restricted and time deposits	31,669	31,624
Cash and cash equivalents	4,079,935	4,459,132
Total current assets	5,515,752	5,832,503
Trade payables	255,321	298,372
Other payables and accruals	759,177	880,447
Interest-bearing bank borrowings	329,972	280,704
Lease liabilities	7,543	4,912
Government grants	57,700	57,563
Due to related parties	12,724	9,125
Income tax payable	18,620	31,115
Total current liabilities	1,441,057	1,562,238
Net working capital	4,074,695	4,270,265
Quick ratio	3.3x	3.3x
Current ratio	3.8x	3.7x
Trade and notes receivables turnover days	46	45
Inventories turnover days	86	90

- *Prepayments, other receivables and other assets* increased from US\$364.0 million on 31 December 2024 to US\$411.2 million on 31 March 2025, mainly due to increased value-added tax credit.
- *Trade payables* decreased from US\$298.4 million on 31 December 2024 to US\$255.3 million on 31 March 2025, primarily due to payments for materials in the period.
- *Other payables and accruals* decreased from US\$880.4 million on 31 December 2024 to US\$759.2 million on 31 March 2025, mainly due to payments for capital expenditures.
- *Interest-bearing bank borrowings* increased from US\$280.7 million on 31 December 2024 to US\$330.0 million, mainly due to increased long term bank borrowings within one year.
- *Income tax payable* decreased from US\$31.1 million on 31 December 2024 to US\$18.6 million on 31 March 2025, mainly due to a payment of income tax.
- On 31 March 2025, *net working capital* was US\$4,074.7 million and the *current ratio* was 3.8.
- *Trade and notes receivables turnover days* were 46.
- *Inventories turnover days* were 86.

Please visit Company's website at www.huahonggrace.com
for further details regarding recent announcements.

Hua Hong Semiconductor Limited
Condensed Consolidated Statements of Profit or Loss
(In US\$ Thousands Except Share Data)

	For the Three Months Ended		
	31-Mar-2025 (Unaudited)	31-Mar-2024 (Unaudited)	31-Dec-2024 (Unaudited)
Revenue	540,937	459,986	539,177
Cost of sales	(490,940)	(430,354)	(477,751)
Gross profit	49,997	29,632	61,426
Other income and gains	30,563	32,851	29,155
Fair value loss on an investment property	-	-	(39)
Selling and distribution expenses	(2,214)	(1,985)	(2,617)
Administrative expenses	(94,896)	(76,535)	(108,009)
Other expenses	(16,208)	(5,907)	(48,745)
Finance costs	(23,301)	(24,585)	(20,406)
Share of profit / (loss) of associates	652	1,411	(433)
Loss before tax	(55,407)	(45,118)	(89,668)
Income tax credit / (expense)	3,245	19,832	(6,596)
Loss for the period	(52,162)	(25,286)	(96,264)
Attributable to:			
Owners of the parent	3,750	31,818	(25,199)
Non-controlling interests	(55,912)	(57,104)	(71,065)
Earnings per share attributable to owners of parent			
Basic	0.002	0.019	(0.015)
Diluted	0.002	0.019	(0.015)
Shares used in calculating basic earnings per share attributable to owners of parent	1,721,931,435	1,716,634,650	1,718,222,223
Shares used in calculating diluted earnings per share attributable to owners of parent	1,728,142,630	1,718,334,991	1,724,086,667

Hua Hong Semiconductor Limited
Condensed Consolidated Statements of Financial Position (In US\$ Thousands)

	As of		
	31-Mar-2025 (Unaudited)	31-Dec-2024 (Audited)	31-Mar-2024 (Unaudited)
ASSETS			
NON-CURRENT ASSETS			
Property, plant and equipment	5,967,555	5,859,117	3,587,363
Investment property	209,257	164,153	166,354
Right-of-use assets	76,359	77,761	79,347
Intangible assets	29,122	31,456	46,526
Investment in associates	140,650	139,799	140,270
Equity instruments designated at fair value through other comprehensive income	289,722	289,311	287,089
Long term prepayment	57,989	21,008	200,074
Deferred tax assets	380	-	501
Total non-current assets	6,771,034	6,582,605	4,507,524
CURRENT ASSETS			
Properties under development	221,061	221,905	194,181
Inventories	468,597	467,060	431,206
Trade and notes receivables	286,763	270,461	306,151
Prepayments, other receivables and other assets	411,207	363,997	53,242
Due from related parties	16,520	18,324	15,688
Restricted and time deposits	31,669	31,624	32,032
Cash and cash equivalents	4,079,935	4,459,132	6,107,986
Total current assets	5,515,752	5,832,503	7,140,486
CURRENT LIABILITIES			
Trade payables	255,321	298,372	239,261
Other payables and accruals	759,177	880,447	379,133
Interest-bearing bank borrowings	329,972	280,704	232,201
Lease liabilities	7,543	4,912	6,257
Government grants	57,700	57,563	41,643
Due to related parties	12,724	9,125	9,704
Income tax payable	18,620	31,115	59,018
Total current liabilities	1,441,057	1,562,238	967,217
NET CURRENT ASSETS	4,074,695	4,270,265	6,173,269
TOTAL ASSETS LESS CURRENT LIABILITIES	10,845,729	10,852,870	10,680,793
Non-current liabilities			
Interest-bearing bank borrowings	1,948,409	1,917,235	1,993,525
Lease liabilities	15,160	18,068	17,714
Deferred tax liabilities	1,498	10,948	2,345
Total non-current liabilities	1,965,067	1,946,251	2,013,584
Net assets	8,880,662	8,906,619	8,667,209
Equity and liabilities capital and reserves			
Share capital	4,957,182	4,938,457	4,934,028
Reserves	1,315,995	1,308,569	1,389,777
Equity attributable to the owners of the company	6,273,177	6,247,026	6,323,805
Non-controlling interests	2,607,485	2,659,593	2,343,404
Total equity	8,880,662	8,906,619	8,667,209

Hua Hong Semiconductor Limited
Condensed Consolidated Statement of Cash Flows (In US\$ Thousands)

	For the Three Months Ended		
	31-Mar-2025 (Unaudited)	31-Mar-2024 (Unaudited)	31-Dec-2024 (Unaudited)
Cash flows from operating activities:			
Loss before tax	(55,407)	(45,118)	(89,668)
Depreciation and amortization	172,126	133,088	142,306
Share of (profit) / loss of associates	(652)	(1,411)	433
Changes in working capital and others	(65,881)	(45,899)	255,037
Net cash flows generated from operating activities	50,168	40,660	308,108
Cash flows from investing activities:			
Payments for property, plant and equipment and intangible assets	(510,851)	(302,574)	(1,505,709)
Receipt of government grants of equipment	-	-	41,149
Other cash flow generated from investing activities	16,560	3,623	20,547
Net cash flows used in investing activities	(494,291)	(298,951)	(1,444,013)
Cash flows from financing activities:			
New bank loans	860,985	103,405	84,551
Proceeds from issue of shares	13,077	114	1,478
Capital contribution from non-controlling interests	-	689,430	-
Repayment of bank borrowings	(811,156)	-	(91,518)
Interest paid	(3,252)	(2,155)	(50,498)
Payment of lease liabilities	(517)	(881)	(401)
Receipt of government grants for interest expenses	-	-	5,459
Net cash flows generated from / (used in) financing activities	59,137	789,913	(50,929)
Net (decrease) / increase in cash and cash equivalents	(384,968)	531,622	(1,186,834)
Cash and cash equivalents, beginning of period	4,459,132	5,585,181	5,766,749
Effects of exchange rate changes	5,771	(8,817)	(120,783)
Cash and cash equivalents, ending of period	4,079,935	6,107,986	4,459,132

As of the date of this announcement, the directors of the Company are:

Executive Directors

Junjun Tang (Chairman)

Peng Bai (President)

Non-Executive Directors

Jun Ye

Guodong Sun

Bo Chen

Chengyan Xiong

Independent Non-Executive Directors

Stephen Tso Tung Chang

Kwai Huen Wong, JP

Songlin Feng

By order of the Board

Hua Hong Semiconductor Limited

Mr. Junjun Tang

Chairman and Executive Director

Hong Kong SAR, PRC

May 8, 2025